

IN THE ABSTRACT OF THE DISCLOSURE:

Please replace the original abstract with the following new abstract:

A vacuum processing method for transferring a wafer to a predetermined position within a vacuum processing chamber using a transfer equipment and performing a predetermined treatment to the wafer in the vacuum processing chamber. The method includes the steps of transferring the wafer in atmospheric air to a vacuum transfer equipment using an atmospheric transfer equipment disposed in atmospheric air, transferring the wafer received from the atmospheric transfer equipment to the predetermined position within the vacuum processing chamber using a vacuum transfer equipment disposed within a vacuum transfer chamber connecting the atmospheric air and the vacuum processing chamber, and detecting displacement of the wafer being transferred using a wafer position sensor disposed near an ingress path leading to the vacuum processing chamber.